

BRCL3550MF
Rev.D Nov.-2020





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CHRG	1	

ž H (I J / Electrical CharacteristicsKL ~ M) * N O Ta=25P O Q1 R S ž T U V ž T)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
	V_{IN}		4.0	5.0	7.0	V
VIN	V_{IN}	$V_{in}>BAT$		100		mV
VIN		$V_{in}>BAT$		30		mV
	V_{float}	$V_{DD}=5V$	4.158	4.20	4.242	V
BAT	I_{bat}	$V_{cc}=3.5V$ $V_{bat}=4.2V$		± 0.5	± 5.0	μA
	V_{TRKL}	V_{BAT}		2.8		V
	V_{TRHYS}			100		mV
VCC	V_{UV}	V_{cc}		3.7		V
VCC	V_{UVHYS}			200		mV
	V_{msd}			1.2		V
	V_{msdHYS}			50		mV
PROG	V_{prog1}			0.1		V
PROG	V_{prog2}			1.0		V
	OTR	$V_{DD}=5V$		130		

< / = > / Application Message

%

? @ A ž B C %

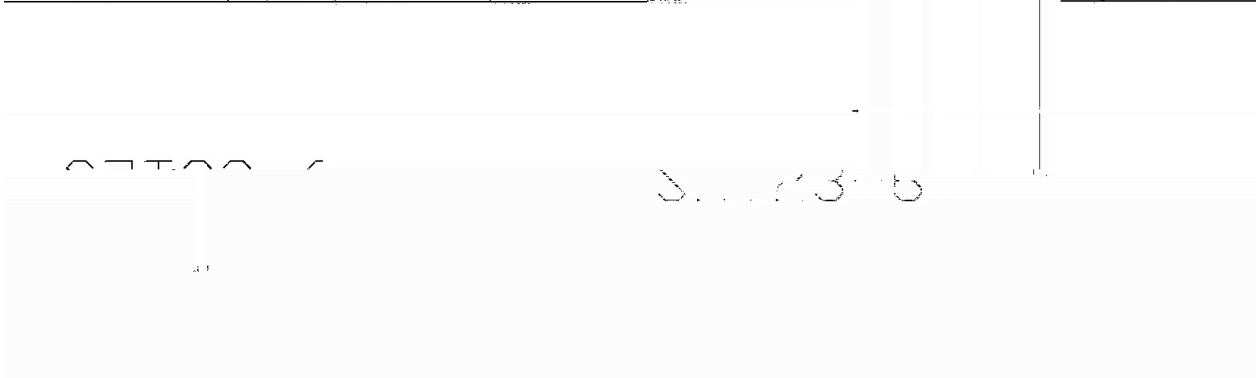
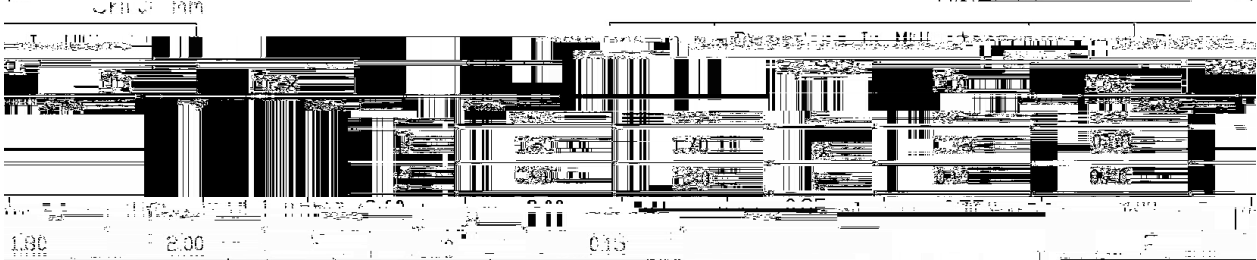
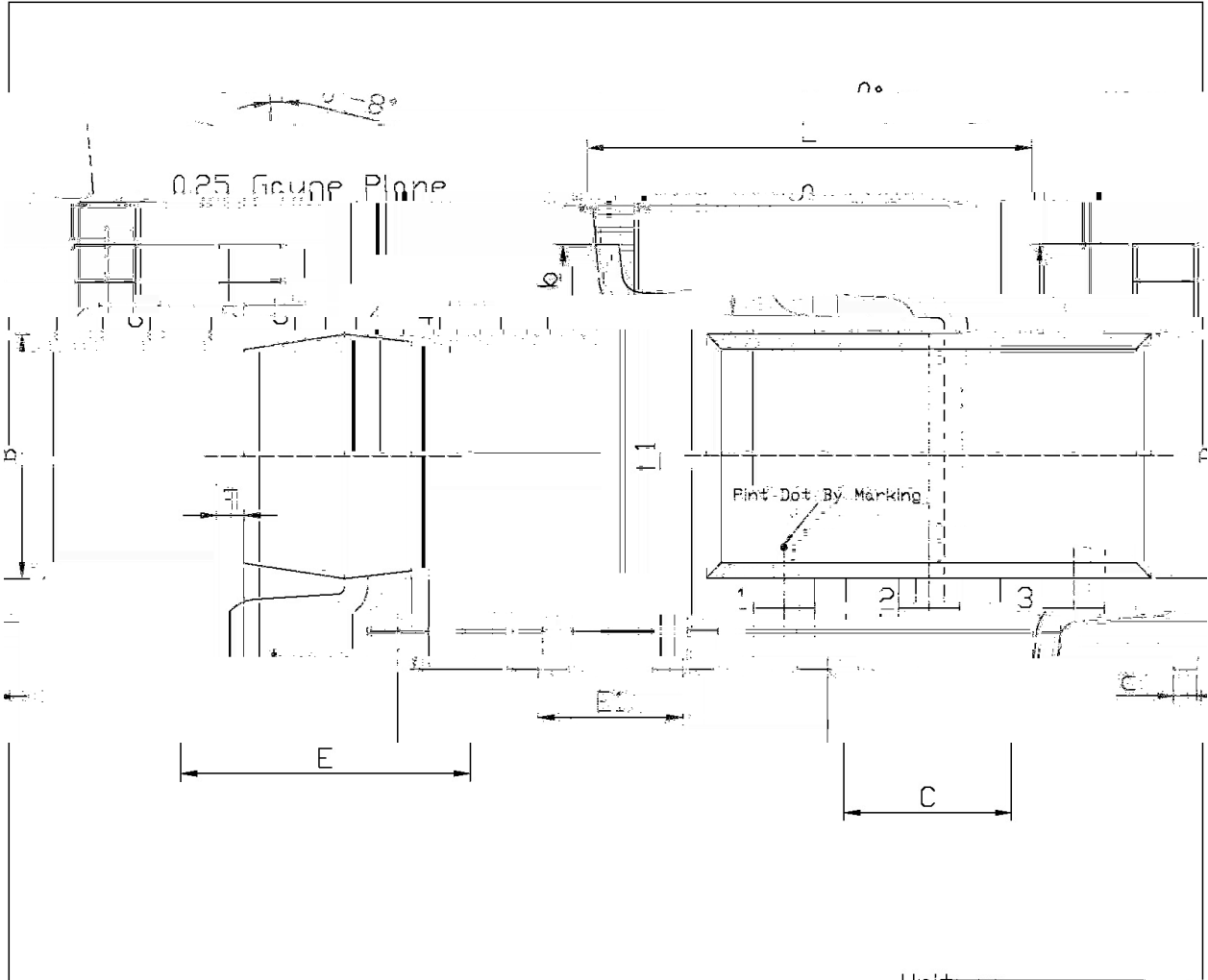
Vcc UVLO PROG 1%
 BAT 2.8V
 BRCL3550MF 1/10
 BAT 2.8V
 BAT 4.20V
 BRCL3550MF 1/10

A ž ž D E F G %

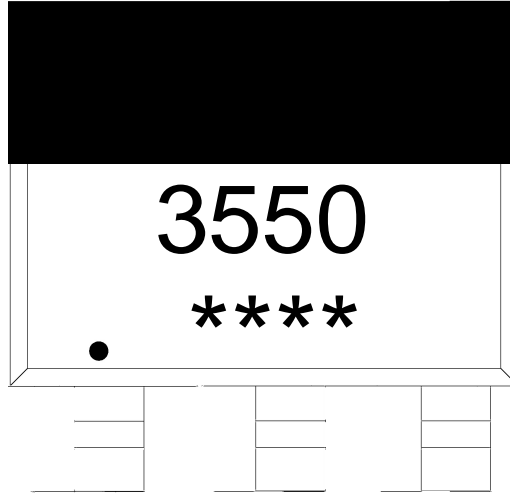
PROG
 $R = 1200/I_{bat}$
 IBAT 0.2A $R = 1200/0.2 = 6000$ RPROG 6k
 1A 0.4A
 RPROG



N s t u v / Package Dimensions



+ ,) * / Marking Instructions



~~000%~~ PIN 1 %
3550

Note:
~~000%~~ PIN 1 Mark%
3550: Product Type Code.
****: Lot No. Code, code change with Lot No.

4. Reflow Soldering (Lead-Free)



Note:

- 1. Preheating: 150~180 °C, Time: 60~90sec.
- 2. Peak Temp.: 245±5 °C, Duration: 5±0.5sec.
- 3. Cooling Speed: 2~10 °C/sec.

5. Resistance to Soldering Heat Test Conditions

260±5 °C, 10±1 sec., Temp.: 260±5 °C, Time: 10±1 sec

6. Packaging SPEC.

6.1 REEL

Package Type	Units					Dimension (unit: mm)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box fl	Outer Box L
SOT23-5/6	3,000	10	30,000	4	120,000	7" x8"	210x205x205	445x230x435

7. Notices